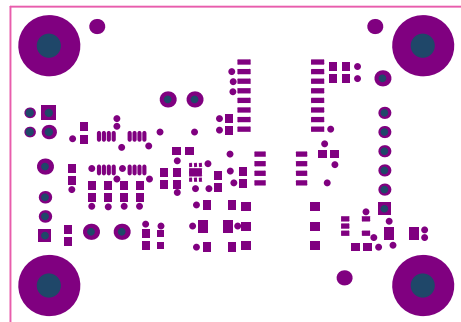
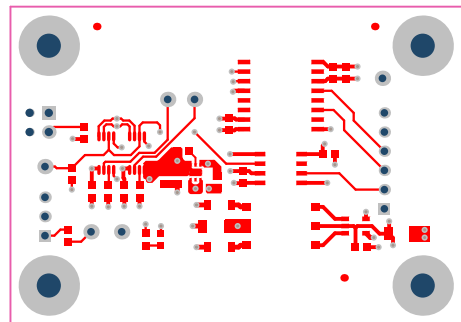


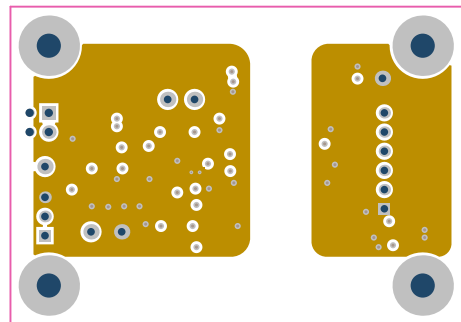
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 7/17/2018 2:13:55 PM	TEXAS INSTRUMENTS	



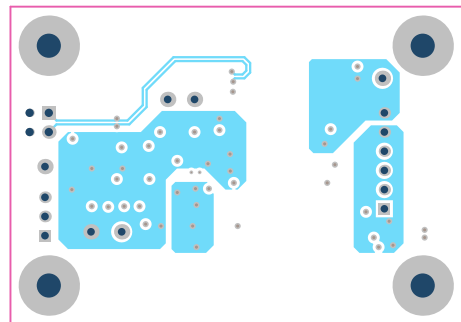
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 7/17/2018 2:13:56 PM	TEXAS INSTRUMENTS	



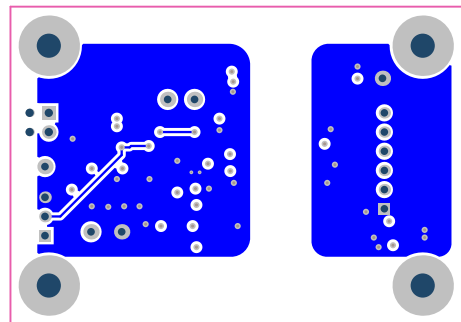
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 7/17/2018 2:13:57 PM	TEXAS INSTRUMENTS	



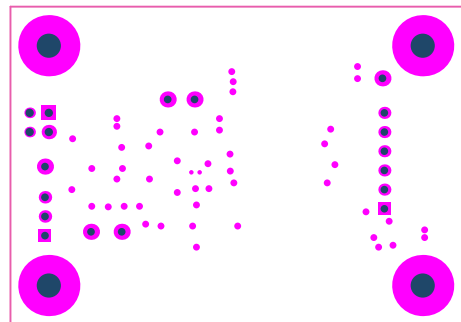
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = GND	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 7/17/2018 2:13:58 PM	TEXAS INSTRUMENTS	



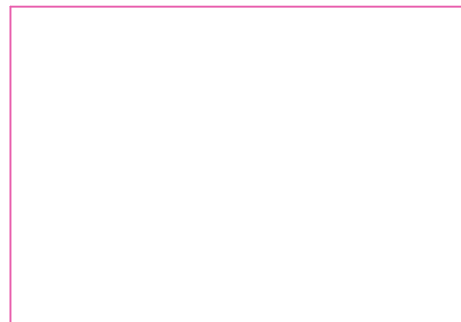
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = PWR	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 7/17/2018 2:13:59 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 7/17/2018 2:14:00 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/17/2018 2:14:01 PM	TEXAS INSTRUMENTS	



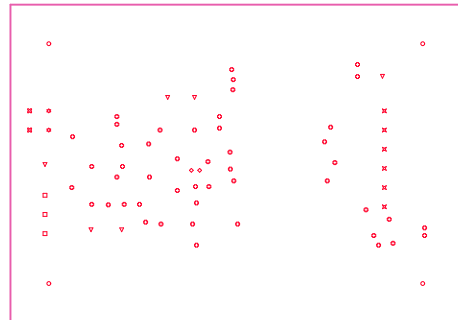
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 7/17/2018 2:14:02 PM		TEXAS INSTRUMENTS

Symbol	Count	Hole Size	Plated	Hole Type
◇	2	7.87mil (0.200mm)	PTH	Round
⊕	48	16.00mil (0.406mm)	PTH	Round
⊗	6	39.37mil (1.000mm)	PTH	Round
▽	6	40.00mil (1.016mm)	PTH	Round
□	3	40.16mil (1.020mm)	PTH	Round
⊗	2	43.31mil (1.100mm)	NPTH	Round
☆	2	43.31mil (1.100mm)	PTH	Round
○	4	125.98mil (3.200mm)	PTH	Round
	73 Total			

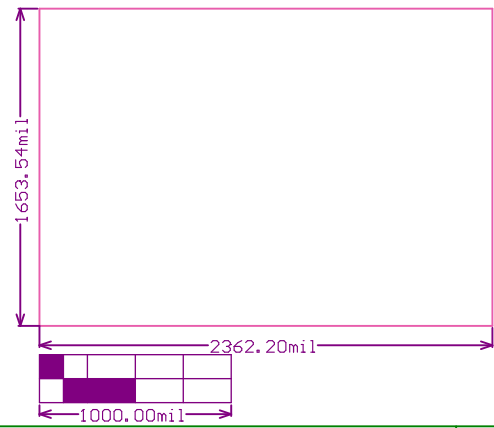
Drill tolerances:

For 16 mil drill via +0/-16 mil
For 7.87 mil drill via +0/-7.87 mil
For PTH +/-3 mil
For NPTH +/-2 mil

Vias are non tented
It is not a impedance controlled board.



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 7/17/2018 2:14:03 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01543	REV: A1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 7/17/2018 2:14:05 PM	TEXAS INSTRUMENTS	

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